IN THE SPECIFICATION:

Please amend paragraph **[0001]** as follows:

[0001] This application is a continuation of application Serial No. 09/920,255, filed August 1, 2001, now U.S. Patent 6,610,162 B1, issued August 26, 2003, which is a continuation of application Serial No. 08/908,425, filed August 7, 1997, now U.S. Patent 6,277,225 B1, issued August 21, 2001, which is a divisional of application Serial No. 08/614,618, filed March 13, 1996, abandoned in favor of application Serial No. 08/908,425, filed August 7, 1997, now U.S. Patent 6,277,225 B1, issued August 21, 2001.

Please amend paragraph **[0029]** as follows:

[0029] FIG. 10 depicts a partial cross-sectional side view of a ~~forth~~ fourth embodiment of a packaged SOJ semiconductor device according to the present invention.

Please amend paragraph **[0037]** as follows:

[0037] FIG. 6A, and in better detail FIG. 6B, depicts, in contrast to the prior art, a packaged LOC arrangement according to the present invention, wherein a single lead end 122 also extends over die 102. Instead of the tight lead-to-die constraint provided by the prior art lead member, a lead 112 having a slot or recess 113 formed therein by etching, machining, eroding, removing material with an electron beam, or other processes known in the art is utilized to reduce the thickness of the lead 112 proximate the active surface 116 of the die 102 between the portion of the lead end 122 attached to the dielectric adhesive 114 and the outer edge 115 of the die 102. The recess 113 creates an enlarged space 117, compared to the prior art device, between the active surface 116 and the lead 112. Thus, a filler particle 130, of same size and shape as that shown with respect to the prior art, while still positioned between the lead 112 and the active surface 116 cannot become lodged therebetween. Moreover, the stacking of such filler particles 130 to create a similar lodging effect is less likely to occur because of the enlarged space 117. The present invention includes cantilevering lead ~~member~~ 112 to extend over the active surface 116 of the die 102 wherein the slot or recess 113 extending along a portion of the

length of the at least one lead ~~member~~ 112 extends over a portion of the active surface 116 to substantially adjacent the outer edge 115 of the die 102.

Please amend paragraph **[0039]** as follows:

[0039] FIGS. 7A and 7B depict an alternative arrangement according to the present invention, wherein the recess 113 formed in the free end 121 of the lead 112 between the lead 112 and the active surface 116 of the die 102 is formed by bending, deforming, or otherwise arching the lead 112 by coining, stamping or other such methods known in the art. As in the embodiment shown in FIGS. 6A and 6B, this ~~recessed portion~~ recess 113 creates additional space between the lead 112 and the die active surface 116 such that a filler particle 130 is less likely to become lodged therein. In addition, the free end 121 of the lead 112 is allowed to deflect about the lead end 122 at the flex point 111 to relieve stress created by stacking of filler particles 130 between the recess 113 and the active surface 116 to reduce the magnitude of point-loading of the filler particle 130 against die active surface 116. As previously stated, the ability of the lead 112 to flex improves the lead locking ability of the dielectric adhesive 114.

Please amend paragraph **[0041]** as follows:

[0041] FIG. 8A depicts an arrangement wherein a lead frame 150, superimposed on a die 102, is secured thereto with dielectric adhesive strips or elongated segments 152 running along each side of active die surface 116. The inner lead ends 122 of the leads 112 thus extend inwardly over adhesive segments 152 toward a row of bond pads 124 running along the center 101 of the die 102. The inner lead ends 122 are then ~~wirebonded~~ wire bonded to the bond pads by wires 151. As shown in FIGS. 9 and 10, filler particles 130 that are stacked may become lodged under a single lead 112 and may thus cause the free end 121 of the lead 112 to be forced away from the active surface 116 of the die 102. However, the greater the enlarged space 117, the less likely it is that filler particles 130 will become stacked in such a way as to cause stress in the lead to die attachment or impinge on the active surface 116 of the die 102.

Please amend paragraph **[0042]** as follows:

[0042] As illustrated in FIGS. 9 and 10, the recess 113 may be of various sizes and configurations and be located in a variety of positions along the lead 112. In FIG. 9, the recess ~~portion~~ 113 extends a relatively small distance into the lead 112, forming a substantially rectangular slot. Moreover, the side wall 153 of the recess is substantially coincident with the outer edge 115 of the die 102. In comparison, the recess 113 shown in FIG. 10 extends farther in depth into the lead 112, forms a substantially trapezoidal slot and has an angled side wall 155 extending a distance away from the outer edge 115 of the die 102. Additionally, the angled side wall 157 forming one side of the slot may be adjacent the edge 159 of the adhesive strip 152, as shown in FIG. 10, or extend beyond the edge 159, as shown in FIG. 9. In any case, the size and shape of the recess 113 may vary according to the process used to form such a recess. For example, such etching may form a recess 113 similar to that shown in FIG. 10 and machining may form a recess similar to that in FIG. 9. The improved flexibility of the lead 112 due to recess 113 enhances the lead locking ability of the adhesive strips or segments 152.